

# Product data sheet

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Semiconductor Compiance

1.1 Technology Data	Symbol		Value	Unit
Maximum allowable continuous AC voltage at 50-60Hz	V <sub>RMS</sub>		18	V
Maximum allowable continuous DC voltage	V <sub>DC</sub>		5	V
Varistor voltage measured *1	Vv		100~150	V
Typical capacitance value measured at 1MHz	С		0.8	pF
Typical capacitance value tolerance			+80-20	%
Maximum ESD allowable clamping Voltage*2	V <sub>CLAMP</sub>	<	240	V
Leakage current at $V_{DC*3}$ (At initial state)	I <sub>LDC</sub>	<	0.1	uA
Leakage current at V <sub>DC*3</sub> (After ESD Test)	I <sub>LDCA</sub>	<	2	uA
1.2 Reference Data				
Response time	T <sub>rise</sub>	<	0.5	ns
Operation ambient temperature			-50 $\sim$ +85	°C
Storage temperature			-50~+125	°C
ESD testing	IEC61000-4-2		Level 4	
1.3 Other Data				
Body			ZnO	
End termination			Ag/Ni/Sn	
Packaging			Reel	
Complies with Standard			IEC61000-4-2	
Complies with RoHs Standard			Yes	
Lead Content		<	1000	ppm
Marking			None	

Notes :

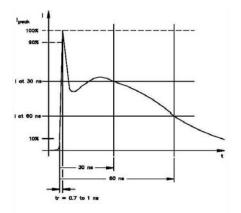
\* 1 The varistor voltage was measured at 1 mA current

\* 2 The Clamping voltage was measured at 8\*20 us standard current.

\* 3 The Leakage current was measured at working voltage.

\* 4 The Energy only for customer reference.

\* 5 The components shall be employed within 1 year, in the nitrogen condition.



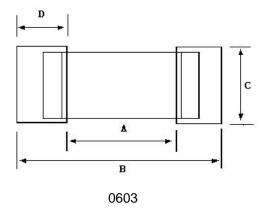
SEVERITY LEVEL	AIRDIRCHARGE	DIRECT
		DISCHARGE
1	2 KV	2 KV
2	4 KV	4 KV
3	8 KV	6 KV
4	15 KV	8 KV

IEC 61000-4-2 Compliant ESD Current Pulse Waveform



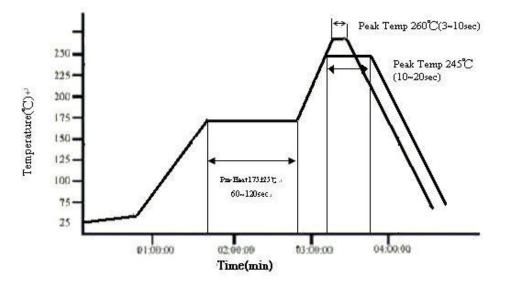
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### PACKAGE MECHANICAL DATA



Dimension	(Unit:	: mm)
	Min.	Max.
А	0.9	1.2
В	2.7	3.2
С	0.7	1.0
D	0.9	1.2

#### The IR reflow and temperature of Soldering for Pb Free



#### ☆ IR reflow Pb Free Process suggestion profile

- (1) The solder recommend is Sn96.5/Ag 3.5 of 120 to 150  $\mu\,{\rm m}$
- (2) Ramp-up rate (217°C to Peak) + 3°C/second max
- (3) Temp. maintain at 175 +/-25 $^{\circ}$ C 180 seconds max
- (4) Temp. maintain above 217 °C 60-150 seconds

#### **REEL SPECIFICATION**

P/N	PKG	QTY
ESD0603E002M05	0603	4000



ESD0603E002M05-MS HF

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